TECH DATA SHEET EC-234 $O \rightarrow CH_3$ $O \rightarrow CH_2$

DESCRIPTION

EC-234 is a phenyl ester epoxy curative hybrid. This unique molecule has the ability to cure with both epoxy resin through the phenyl ester or in a free radical resin system through the acrylate. The low viscosity makes it an excellent diluent. The hybrid nature of the molecule allows for versatility in the cure giving way to a multitude of applications.

HIGHLIGHTS

Hybrid cure

· Low viscosity

TYPICAL PHYSICAL AND CHEMICAL PROPERTIES

PROPERTY	METHOD	RESULT
Appearance at Room Temperature	Visual	Light yellow liquid
Viscosity @ 25°C (typical)	Haake Rheometer	40 cP
Density		1.14g/cc
Functionality		2
Molecular Weight (approx.)		234 daltons
Recommended Storage Temp		10°C or below

Data is for reference only and may vary depending on testing method used. The structure shown above is an idealized representation of a statistical distribution.

RECOMMENDED FORMULATION USE:

EC-234 is recommended for use as a curative in epoxy systems and/or free-radically cured systems. EC-234 can cure both with standard free-radical initiators and epoxy catalysts such as imidizoles, amines, and Lewis acids.

CONTACT:

REQUEST A SAMPLE OR PLACE AN ORDER

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